Figures 6 and 7, respectively.

The method of solution for a hollow wafer was described in an earlier section, and its discussion was resumed in the section "Future Work". The merits of having this solution have been pointed out, and a continuing effort will be made to carry it to completion. The program for use in computing the displacement coefficients is shown in Figure 27, and is completely analogous to that contained in Figure 21. The exception being that the added length of the boundary condition equations creates an overflow in the memory storage of the IBM 1620 computer. With an appropriate change in the input-output statements of the current program, it can be run on the IBM 7090, and it is the present intent to do so in the near future. The required stress and force programs have not been shown since their operation depends upon the availability of the output data from the coefficients program.